

IN THE CLAIMS

1. (Original) A method of cooling a semiconductor die, comprising the steps of:
flowing fluid through micro-channels formed into the die;
communicating fluid from the die to a condenser arranged above the die;
cooling fluid at the condenser; and
communicating fluid from the condenser to the micro-channels.
2. (Original) A method of claim 1, the step of flowing comprising flowing fluid through the micro-channels bounded, at least in part, by a semiconductor element coupled with the die.
3. (Original) A method of claim 2, the semiconductor element comprising one of silicon and a glass plate.
4. (Original) A method of claim 1, further comprising the step of shaping the micro-channels for preferential fluid flow along the micro-channels.
5. (Original) A method of claim 1, the steps of communicating comprising utilizing headers coupled with the micro-channels.
6. (Currently Amended) A method of claim 1, the step of communicating fluid from the condenser to the micro-channels comprising utilizing gravity to force the fluid to the [condenser]die.